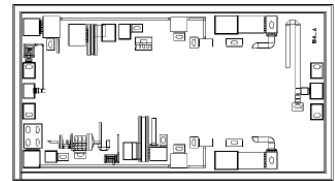


**AMT1112**  
**8 – 12GHz Power Amplifier Chip**



**Key Features :**

- Frequency range : 8 – 12GHz
- Typical small signal gain : 28dB
- Typical output power : 35.5dBm
- Typical power added efficiency (PAE) : 40%
- Voltage Bias : 8V, -0.7V
- Chip dimensions : 2.8mm x 1.5mm x 0.1mm
- Applications : wireless communication, transceiver module, radio telecommunication etc.

**Description :**

AMT1112 chip is designed by Gallium Arsenide (GaAs) pHEMT process, a high performance 8 - 12GHz power amplifier, it uses dual voltage operation, with drain voltage V<sub>d</sub> at 8.0V, it offers 35dBm power output in the frequency range of 8 – 12GHz. This chip is designed with ground through metal vias on the back technology. All chip products are 100% RF tested.

**Absolute Maximum Ratings (Ta = 25°C)**

Symbol	Parameter	Value	Remark
V <sub>d</sub>	Drain Voltage	9V	
I <sub>d</sub>	Drain Current	2A	
V <sub>g</sub>	Gate Voltage	-0.5V	
I <sub>g</sub>	Gate Current	50mA	
P <sub>d</sub>	Power Dissipation	16W	
P <sub>in</sub>	Input Signal Power	25dBm	
T <sub>ch</sub>	Operating Temperature	150°C	
T <sub>m</sub>	Sintering Temperature	310°C	30s, N <sub>2</sub> protection
T <sub>stg</sub>	Storage Temperature	-65 ~ +150°C	

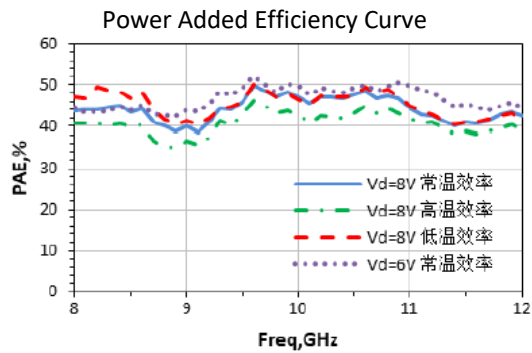
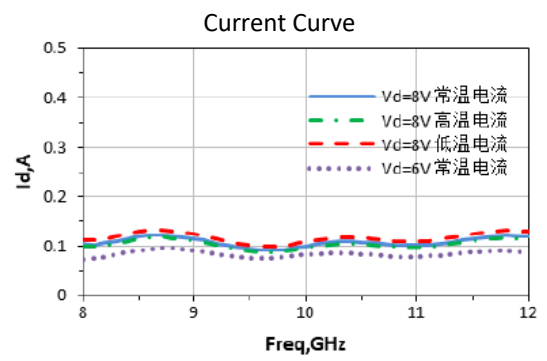
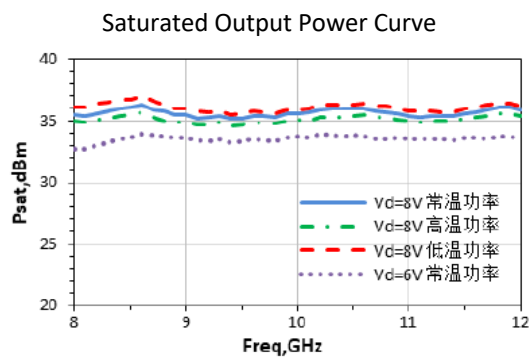
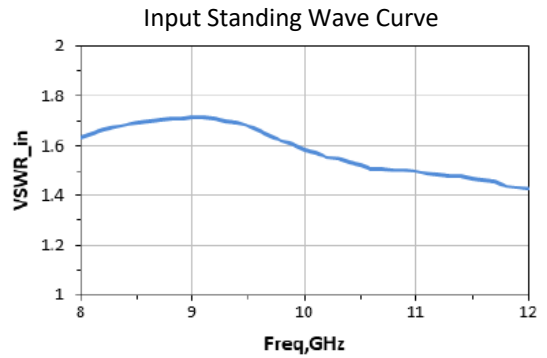
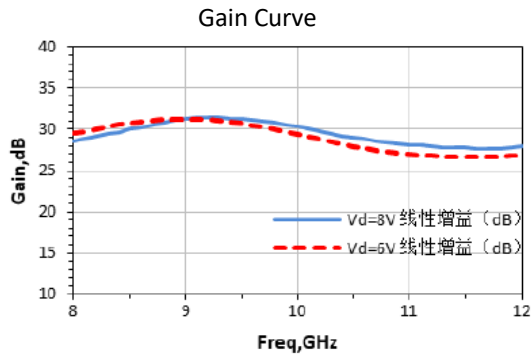
[1] Operation outside any of the Absolute Maximum Ratings may cause permanent device damage.

**Electrical Characteristics (Ta = 25°C)**

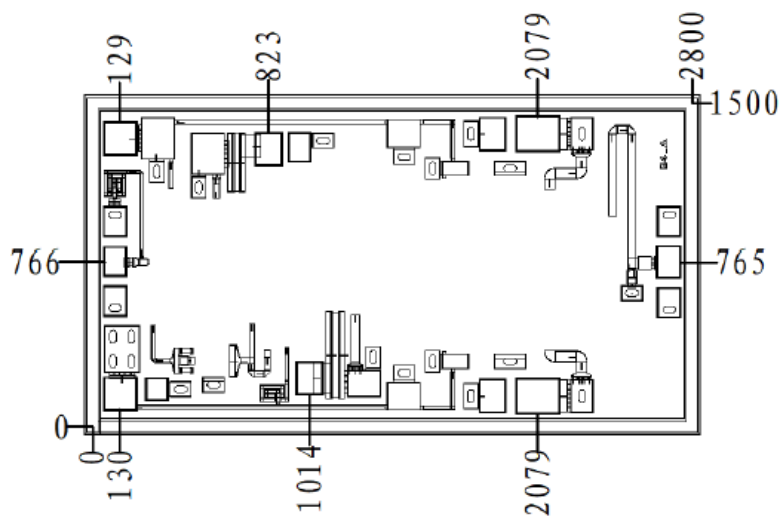
Symbol	Parameter	Test Condition	Value			Unit
			Min	Typical	Max	
G	Small Signal Gain	V <sub>d</sub> = 8V V <sub>g</sub> = -0.7V F : 8 ~ 12GHz	25	28	-	dB
VSWR <sub>i</sub>	Input Standing Wave		-	1.8	2	
P <sub>out</sub>	Saturated Power Output		34.5	35.5	36.5	dBm
PAE	Power Added Efficiency		38	40	-	%
I <sub>D</sub>	Dynamic Current		-	1.2	1.3	A
I <sub>J</sub>	Static Current		-	1	1.1	A

Note, no CW operation.

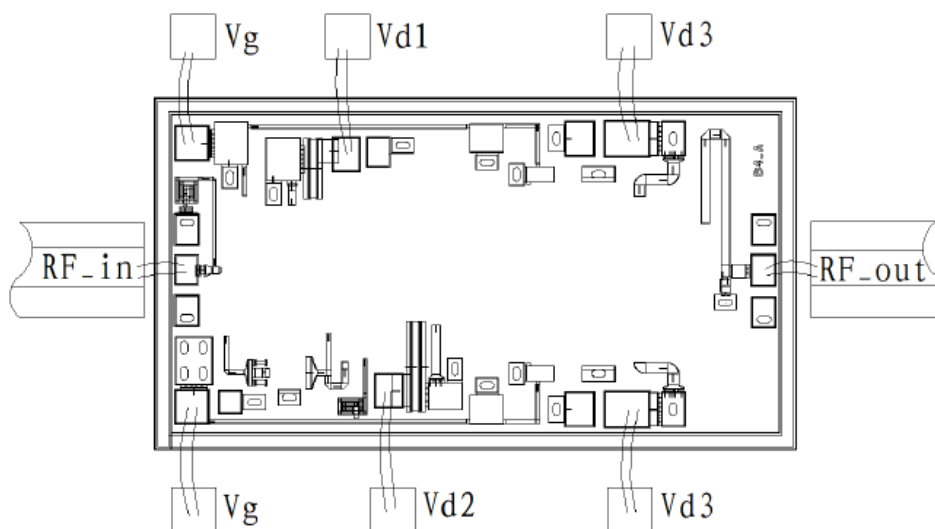
### Typical Performance



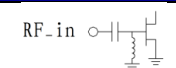
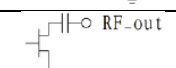
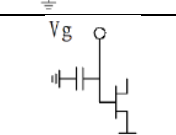
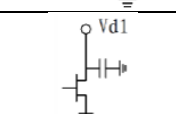
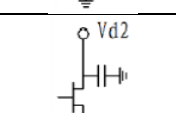
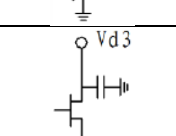
### Chip Dimensions (Unit : $\mu\text{m}$ )



### Chip Layout Diagram



### Pad Definition

Symbol	Function	Dimension	Equivalent Circuit
RF_in	RF signal input port, connecting to external 50Ω system. DC blocking capacitor is needed, if external DC current is applied to this pad.	100*128μm <sup>2</sup>	
RF_out	RF signal output port, connecting to external 50Ω system, no need to add DC blocking capacitor.	110*138μm <sup>2</sup>	
Vg	Amplifier gate bias, need external 100pF, 1000pF capacitor.	150*150μm <sup>2</sup>	
Vd1	Amplifier drain bias, need external 100pF, 1000pF capacitor.	120*150μm <sup>2</sup>	
Vd2	Amplifier drain bias, need external 100pF, 1000pF capacitor.	120*150μm <sup>2</sup>	
Vd3	Amplifier drain bias, need external 100pF, 1000pF capacitor.	200*160μm <sup>2</sup>	

Please see Appendix A for details.